### THERMAL RESISTANCES

Symbol	Parameter	Value	Unit
Rth (j-c) DC	Junction to case for DC	1.5	°C/W
Rth (j-c) AC	Junction to case for 360° conduction angle (F= 50 Hz)	1.1	°C/W

# **GATE CHARACTERISTICS** (maximum values)

 $P_{G}$  (AV) = 1W  $P_{GM}$  = 40W (tp = 20  $\mu s$ )  $I_{GM}$  = 8A (tp = 20  $\mu s$ )  $V_{GM}$  = 16V (tp = 20  $\mu s$ ).

# **ELECTRICAL CHARACTERISTICS**

Symbol	Test Conditions		Quadrant		Suffix		Unit
					Α	В	
IGT	V <sub>D</sub> =12V (DC) R <sub>L</sub> =33Ω	Tj=25°C	1-11-111	MAX	100	50	mA
			IV	MAX	150	100	
VGT	V <sub>D</sub> =12V (DC) R <sub>L</sub> =33Ω	Tj=25°C	I-II-III-IV	MAX	1.	.5	V
VGD	VD=VDRM RL=3.3kΩ	Tj=125°C	I-II-III-IV	MIN	N 0.2		V
tgt	$VD=VDRM$ $IG = 500mA$ $dI_G/dt = 3A/\mu s$	Tj=25°C	I-II-III-IV	TYP	2.5		μs
IL	I <sub>G</sub> =1.2 I <sub>G</sub> T	Tj=25°C	I-III-IV	TYP	70	60	mA
			П		200	180	
I <sub>H</sub> *	I <sub>T</sub> = 500mA gate open	Tj=25°C		MAX	100	80	mA
V <sub>TM</sub> *	I <sub>TM</sub> = 42A tp= 380μs	Tj=25°C		MAX	1.8		V
IDRM				MAX	0.0	01	mA
IRRM	VRRM Rated	Tj=125°C		MAX	(	6	
dV/dt *	Linear slope up to V <sub>D</sub> =67%V <sub>DRM</sub> gate open	Tj=125°C		MIN	25	50	V/μs
(dV/dt)c *	(dl/dt)c = 13.3A/ms	Tj=125°C		MIN	1	0	V/μs

 $<sup>^{\</sup>star}$  For either polarity of electrode A2 voltage with reference to electrode A1.

### ORDERING INFORMATION

Package	IT(RMS)	V <sub>DRM</sub> / V <sub>RRM</sub>	Sensitivity Specification	
	Α	V	Α	В
ВТА	30	400	X	X
(Insulated)		600	X	X
		700	X	X
		800	X	X

**Fig.1**: Maximum RMS power dissipation versus RMS on-state current (F=50Hz). (Curves are cut off by (dl/dt)c limitation)

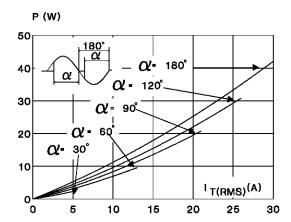


Fig.2 : Correlation between maximum RMS power dissipation and maximum allowable temperatures ( $T_{amb}$  and  $T_{case}$ ) for different thermal resistances heatsink + contact.

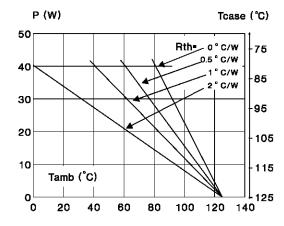
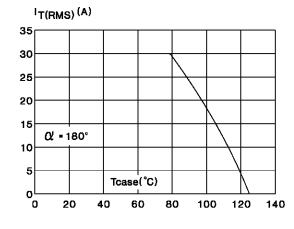


Fig.3: RMS on-state current versus case temperature.



**Fig.4**: Relative variation of thermal impedance junction to case versus pulse duration.

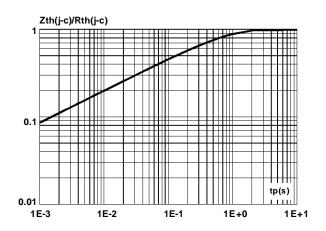
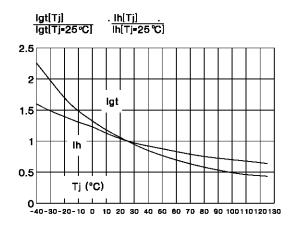


Fig.5: Relative variation of gate trigger current and holding current versus junction temperature.



**Fig.7 :** Non repetitive surge peak on-state current for a sinusoidal pulse with width :  $t \le 10 ms$ , and corresponding value of  $I^2t$ .

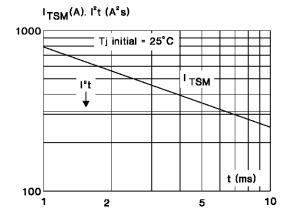


Fig.6: Non Repetitive surge peak on-state current versus number of cycles.

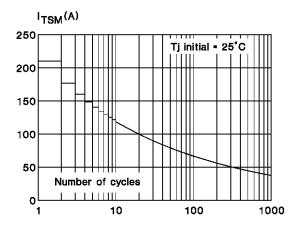
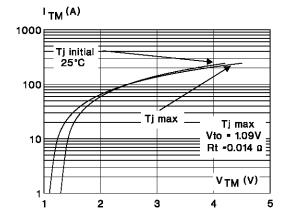
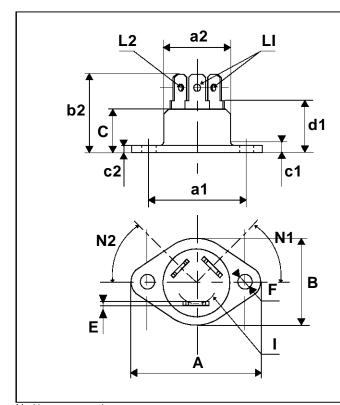


Fig.8 : On-state characteristics (maximum values).



# **PACKAGE MECHANICAL DATA**

RD91 Plastic



REF.	DIMENSIONS				
	Millimeters		Inc	hes	
	Min.	Max.	Min.	Max.	
Α		40.00		1.575	
a1	29.90	30.30	1.177	1.193	
a2		22.00		0.867	
В		27.00		1.063	
b1	13.50	16.50	0.531	0.650	
b2		24.00		0.945	
С		14.00		0.551	
с1		3.50		0.138	
c2	1.95	3.00	0.077	0.118	
E	0.70	0.90	0.027	0.035	
F	4.00	4.50	0.157	0.177	
I	11.20	13.60	0.441	0.535	
L1	3.10	3.50	0.122	0.138	
L2	1.70	1.90	0.067	0.075	
N1	33°	43°	33°	43°	
N2	28°	38°	28°	38°	

Marking : type number Weight : 20 g

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